

Features

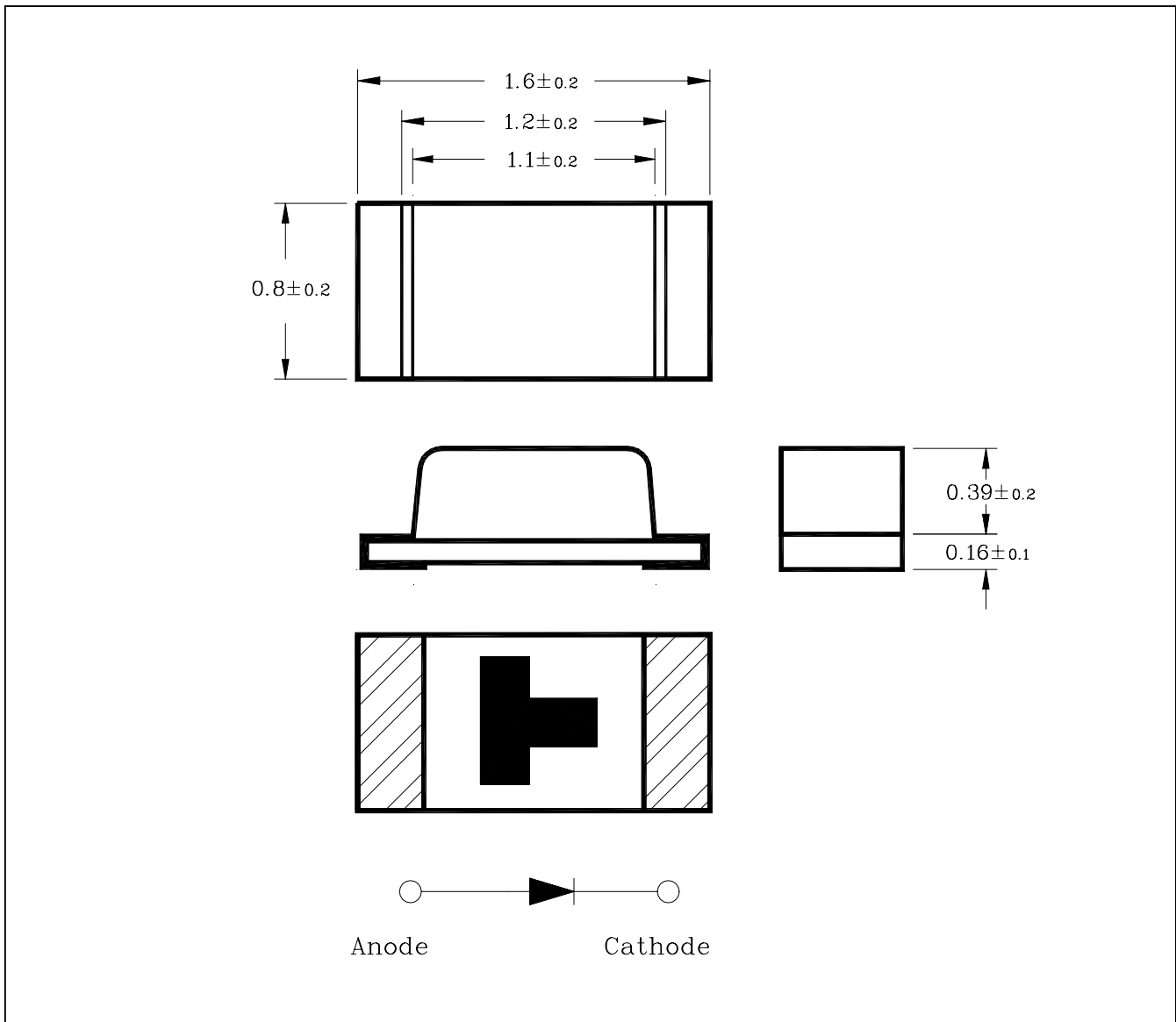
- 1.6mm(L)×0.8mm small size surface mount type
- Thin package of 0.55mm(H) thickness
- Transparent clear lens optic
- Low power consumption type chip led

Applications

- LCD backlighting
- Keypad backlighting
- Symbol backlighting
- Front panel indicator lamp

Outline Dimensions

unit : mm



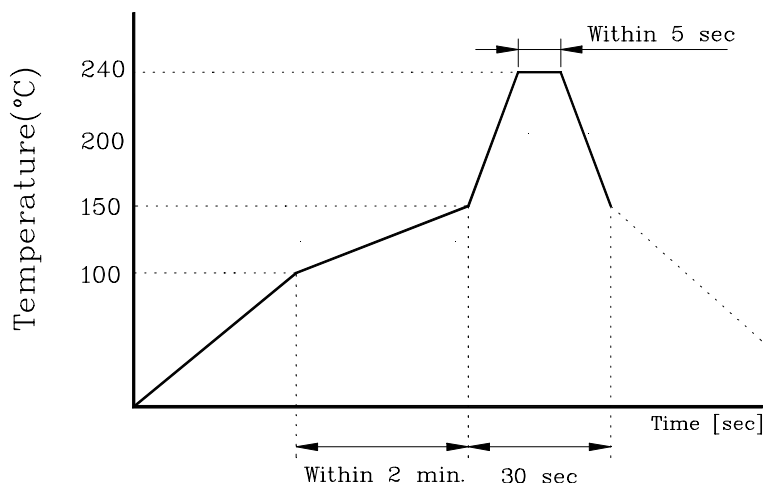
Absolute maximum ratings

Characteristic	Symbol	Ratings	Unit
Power Dissipation	P_D	70	mW
Forward Current	I_F	25	mA
*1Peak Forward Current	I_{FP}	50	mA
Reverse Voltage	V_R	4	V
Operating Temperature	T_{opr}	-25 80	
Storage Temperature	T_{stg}	-30 100	
*2Soldering Temperature	T_{sol}	240 for 5 seconds	

*1.Duty ratio = 1/16, Pulse width = 0.1ms

*2.Recommended soldering Temperature Profile

- 2-1) Preheating 100 to 150 within 2 minutes Soldering 240 within 5 seconds
- Gradual cooling (Avoid quenching)



Electrical Characteristics

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 20\text{mA}$	-	2.2	2.8	V
Luminous Intensity	I_V	$I_F = 20\text{mA}$	-	3	-	mcd
Peak Wavelength	λ_P	$I_F = 20\text{mA}$	-	585	-	nm
Spectrum Bandwidth		$I_F = 20\text{mA}$	-	30	-	nm
Reverse Current	I_R	$V_R = 4\text{V}$	-	-	10	μA
*3Half angle	$\theta_{1/2}$	$I_F = 20\text{mA}$	-	± 65	-	deg
	X'-Y'		-	± 70	-	

Characteristic Diagrams

Fig. 1 $I_F - V_F$

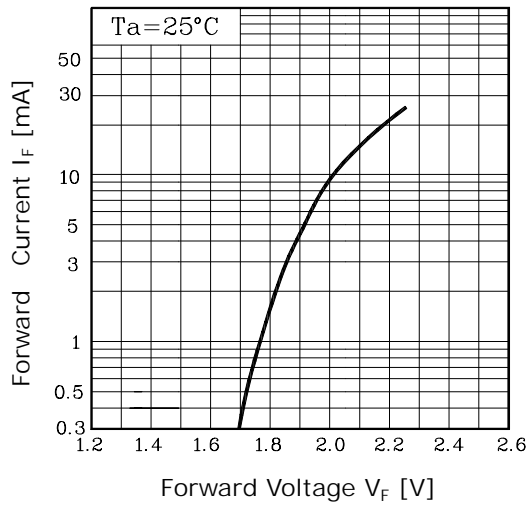


Fig. 2 $I_V - I_F$

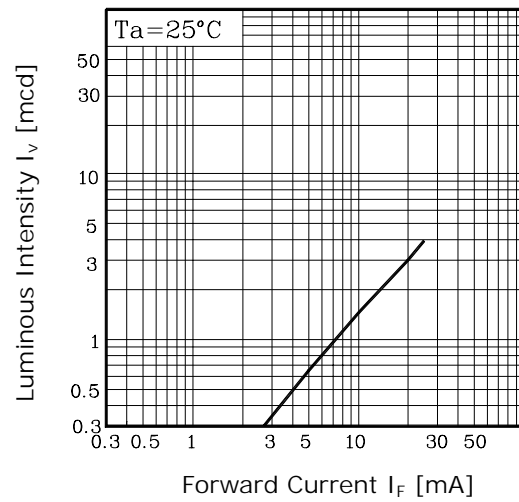


Fig. 3 $I_F - T_a$

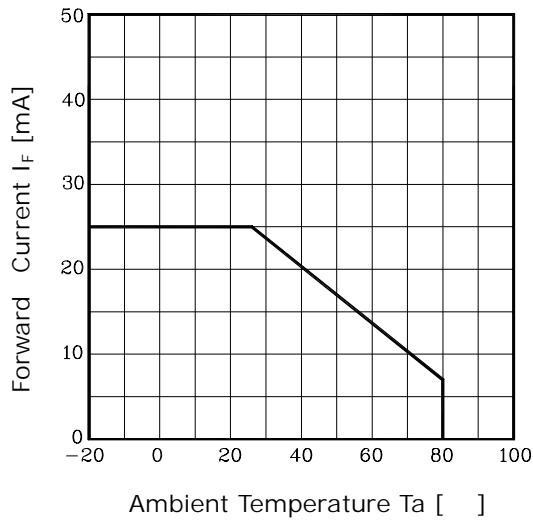


Fig.4 Spectrum Distribution

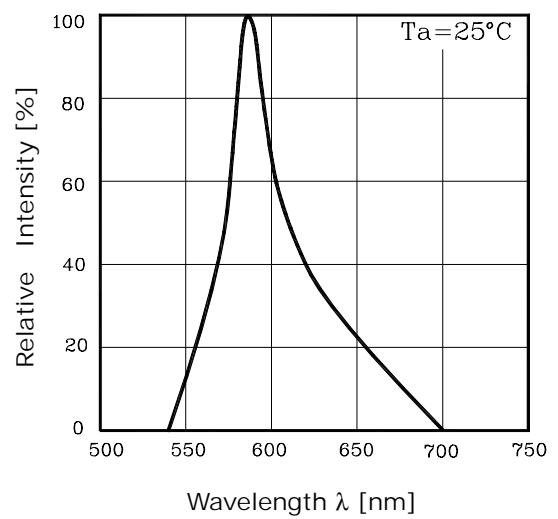


Fig. 5-1 Radiation Diagram(X)

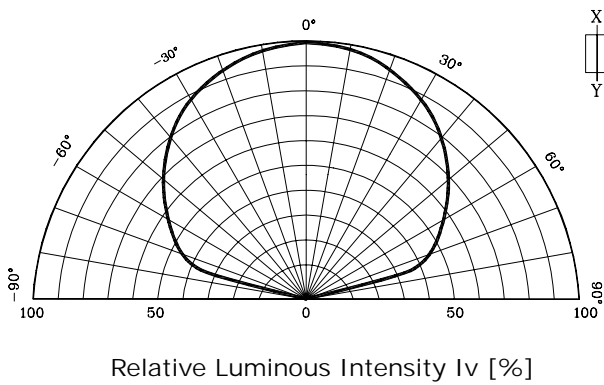


Fig. 5-2 Radiation Diagram(Y)

